AMENDED CLAIM SET

1. (Original) A compositive laminate substrate, comprising:

at least an inorganic substrate having at least a passive component formed thereon; and

two organic substrates, located on two sides of said inorganic substrate, having circuits for electrical connections between outer input/output ports and said passive component of said inorganic substrate through said organic substrates.

2. (Original) The compositive laminate substrate according to claim 1 wherein the material of said inorganic substrate is selected from the group consisting of ceramic, silicon and glass.

3. (Currently Amended) The compositive laminate substrate according to claim 2 wherein, ~~with~~ when said inorganic substrate is ceramic material, said passive component is made from the process selected from the group consisting of thick film process and thin film process.

4. (Currently Amended) The compositive laminate substrate according to claim 2 wherein, ~~with~~ when said inorganic substrate is silicon material, said passive component is made from a semiconductor fabrication process.

5. (Original) The compositive laminate substrate according to claim 1 wherein said passive component is selected from the group consisting of capacitor, inductor and resistor.

6. (Original) The compositive laminate substrate according to claim 1 wherein each of said organic substrate is composed of a plurality of print circuit boards.

7. (Original) The compositive laminate substrate according to claim 6 wherein the circuit of the print circuit boards are made separately, and then stacked together to form said organic substrates.

8. (Original) The compositive laminate substrate according to claim 6 wherein the circuit of the print circuit boards are made separately, then stack the print circuit boards together, and finally form the circuit of a surface layer with build-up process to form said organic substrates.

9. (Original) The compositive laminate substrate according to clam 1 wherein at least one of said organic substrate further comprises at least a passive component.

10. (Original) The compositive laminate substrate according to claim 9 wherein said passive component on said organic substrate is selected from the group consisting of capacitor, inductor and resistor.

11. (Original) The compositive laminate substrate according to claim 1 wherein said organic substrate is made on said inorganic substrate with build-up process.

12. (Original) The compositive laminate substrate according to claim 1 further comprises a covering layer, for covering said inorganic substrate, integrating with said organic substrate, and fully embedding said inorganic substrate in said the organic substrate, said covering layer further comprises circuits for providing electrical connections between said passive component and said organic substrate.

13. (Original) The compositive laminate substrate according to claim 1 further comprises a bonding layer formed between said inorganic substrate and at least one of said organic substrate for bonding the two.

14. (Original) A compositive laminate substrate, comprising:

an inorganic substrate having at least a passive component formed thereon; and

an organic substrate, located on one side of said inorganic substrate, having circuits for electrical connections between outer input/output ports and said passive component on said inorganic substrate.

15. (Original) The compositive laminate substrate according to claim 14 wherein material of said inorganic substrate is selected from the group consisting of ceramic, silicon and glass.

16. (Currently Amended) The compositive laminate substrate according to claim 15 wherein, ~~with~~ when said inorganic substrate is ceramic material, said passive component is made from a process selected from the group consisting of thick film process and thin film process.

17. (Currently Amended) The compositive laminate substrate according to claim 15 wherein, ~~with~~ when said inorganic substrate is silicon material, said passive component is made from a semiconductor fabrication process.

18. (Original) The compositive laminate substrate according to claim 14 wherein said passive component is selected from the group consisting of capacitor, inductor and resistor.

19. (Original) The compositive laminate substrate according to claim 14, wherein said organic substrate is composed of a plurality of print circuit boards.

20. (Original) The compositive laminate substrate according to claim 19 wherein the circuit of said print circuit boards of said organic substrate are made separately, and then stacked together to form said organic substrate.

21. (Original) The compositive laminate substrate according to claim 19 wherein the circuit of said print circuit boards of said organic substrate are made separately, then stack the print circuit boards together, and finally form the circuit of a surface layer with build-up process to form said organic substrate.

22. (Original) The compositive laminate substrate according to claim 14 wherein said organic substrate further comprises at least a passive component.

23. (Original) The compositive laminate substrate according to claim 22 wherein said passive component on said organic substrate is selected from the group consisting of capacitor, inductor and resistor.

24. (Original) The compositive laminate substrate according to claim 14 wherein said organic substrate is made on said inorganic substrate with build-up process.

25. (Original) The compositive laminate substrate according to claim 14 further comprises a bonding layer formed between said inorganic substrate and said organic substrate for bonding the two.